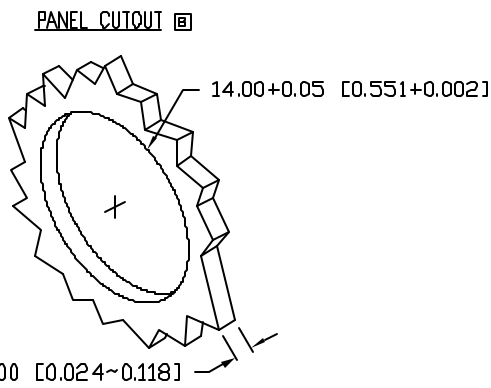
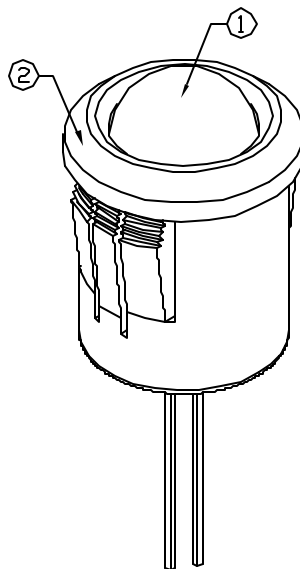
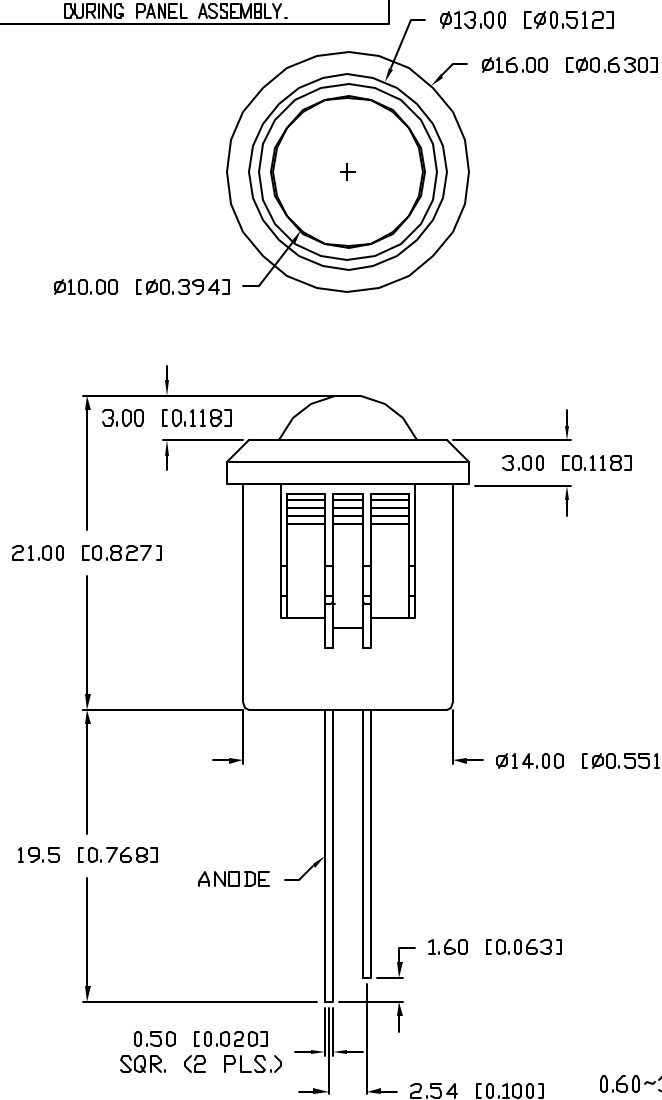


UNCONTROLLED DOCUMENT

CAUTION: PRESSURE SENSITIVE ASSEMBLY
AVOID APPLYING PRESSURE TO LED
DURING PANEL ASSEMBLY.



PART NUMBER
SSI-LXH1090GD

REV.
C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR.	10.9.97
B	E.C.N. #10539.	9.24.99
C	E.C.N. #10BRDR. & REDRAWN IN 3D.	1.5.02

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		30		mcad	$I_f=20\text{mA}$
VIEWING ANGLE		60		$2x$ theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	GREEN DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

* $t < 10\mu\text{s}$

NOTES:

- SSL-LX1001336D LED.
- SSH-RTF1090 HOLDER.
- UV EPOXY TO RETAIN LED IN HOLDER.

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= ± 1 (± 0.039), XX= ± 0.5 (± 0.020), XXX= ± 0.25 (± 0.010), XXXX= ± 0.127 (± 0.005). LEAD SIZE= ± 0.05 (± 0.002), LEAD LENGTH= ± 0.75 (± 0.030), MIN= $\frac{+0.00}{-0.00}$ DECIMAL PRECISION MAX= $\frac{+0.00}{-0.00}$ DECIMAL PRECISION

REV.
C

PART NUMBER
SSI-LXH1090GD

CONFIDENTIAL INFORMATION
THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC, THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.



290 E. HELEN ROAD
PALATINE, IL 60067-6976
PHONE: +1.847.359.2790
US WEB: www.lumex.com
TW WEB: www.lumex.com.tw

T-10mm 565nm GREEN LED PANEL INDICATOR,
GREEN DIFFUSED LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC
CHECKED BY:
APPROVED BY:
DATE: 7.14.93
PAGE: 1 OF 1
SCALE: N/A